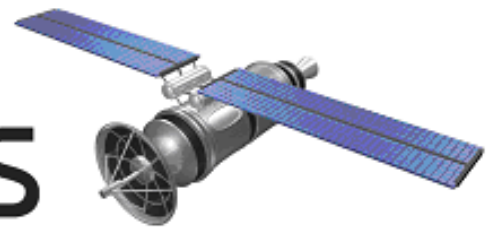


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The Global Semiconductor Industry Analysts

FH MONDAY

16 January 2023

T-Mobile Puts Speed at the Top of its Standalone 5G

T-Mobile is once again ahead of the pack when it comes to pure standalone 5G in the United States. Following its 600MHz nationwide 5G network launch in August 2020, T-Mobile has now converted its 2.5GHz mid-band network—which the company markets as “ultra-capacity”—to run on a 5G core.

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NXP Semiconductors: Launch Of Wireless MCUs Should Accelerate The Growth

NXP Semiconductors (NASDAQ:NXPI) is a world-leading semiconductor company mainly focusing on the development of products for primary end markets such as Automotive, Industrial and IoT, Mobile and Communication Infrastructure.

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Analog Devices and Seeing Machines Collaborating on ADAS Solutions

Analog Devices Inc. and Seeing Machines are collaborating to support high-performance driver and occupant monitoring system (DMS/OMS) technology. Long-haul driving and congested traffic are two scenarios where driver fatigue and distraction often occur and frequently cause accidents, resulting in injury or worse.

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TALK TO US



STMicroelectronics Automotive-grade Devices Feature Enhanced Power Densities

STMicroelectronics has introduced five power-semiconductor bridges in popular configurations, housed in its advanced ACEPACK SMIT package that eases assembly and enhances power density over conventional TO-style packages..

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VinFast and NXP collaborating on next-gen smart EVs

VinFast and NXP Semiconductors announced their collaboration on VinFast's next-generation of automotive applications at this year's Consumer Electronics Show (CES). The collaboration supports VinFast's goal in developing smarter, cleaner and connected electric vehicles.

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T-Mobile Puts Speed at the Top of its Standalone 5G Goals

T-Mobile is once again ahead of the pack when it comes to pure standalone 5G in the United States.

Following its 600MHz nationwide 5G network launch in August 2020, T-Mobile has now converted its 2.5GHz mid-band network—which the company markets as “ultra-capacity”—to run on a 5G core. T-Mobile said that this network, which launched in November 2022, covers more than 250 million people in the U.S., and puts the carrier ahead on standalone 5G in the U.S.

Meanwhile, carriers worldwide are just starting to move to standalone 5G. The 3rd Generation Partnership Project (3GPP) completed its initial standalone 5G specification in September 2018. Yet AT&T, Verizon and most other major mobile network operators (MNOs) worldwide still rely on a non-standalone (NSA) 5G network for their commercial 5G services.

NXP Semiconductors: Launch Of Wireless MCUs Should Accelerate The Growth

NXP Semiconductors (NASDAQ:NXPI) is a world-leading semiconductor company mainly focusing on the development of products for primary end markets such as Automotive, Industrial and IoT, Mobile and Communication Infrastructure. The company has recently expanded its Matter portfolio with the addition of two new devices which I believe can act as a primary catalyst to boost its growth as I think it is a "first of its kind" MCU in the industry which can have high demand in the market.

NXP Semiconductors is a semiconductor business which operates globally and is one of the long-established suppliers in the industry known for innovation with an operating history of over 50 years.

Analog Devices and Seeing Machines Collaborating on ADAS Solutions

Analog Devices Inc. and Seeing Machines are collaborating to support high-performance driver and occupant monitoring system (DMS/OMS) technology.

Long-haul driving and congested traffic are two scenarios where driver fatigue and distraction often occur and frequently cause accidents, resulting in injury or worse. New and sophisticated advanced driver assistance systems (ADAS) are rapidly evolving to support safety across increasing, varied levels of autonomous capability.

The collaboration pairs ADI's advanced infrared driver and high-speed Gigabit Multimedia Serial Link (GMSL) camera connectivity solutions with Seeing Machines' artificial intelligence (AI) DMS and OMS software to support powerful eye gaze, eyelid, head, and body-pose tracking system technology that more accurately monitors driver fatigue and distraction.

STMicroelectronics Automotive-grade Devices Feature Enhanced Power Densities

STMicroelectronics has introduced five power-semiconductor bridges in popular configurations, housed in its advanced ACEPACK SMIT package that eases assembly and enhances power density over conventional TO-style packages.

Engineers can choose from two STPOWER 650V MOSFET half bridges, a 600V ultrafast diode bridge, a 1.2kV half-controlled full-wave rectifier, and a 1.2kV thyristor-controlled bridge leg. All devices meet automotive-industry requirements and are suitable for electric vehicle on-board chargers (OBC) and DC/DC converters, as well as industrial power conversion.

ST's ACEPACK SMIT surface mounted package delivers the easy handling of an insulated package with the thermal efficiency of an exposed drain. It allows direct-bonded copper (DBC) die attachment for efficient top-side cooling. The 4.6cm² exposed metal top-side of the ACEPACK SMIT permits easy attachment of a planar heatsink. This creates a space-saving low profile that maximizes thermal dissipation for greater reliability at high power. The module and heatsink can be placed using automated inline equipment, which saves manual processes and boosts productivity.

VinFast and NXP collaborating on next-gen smart EVs

VinFast and NXP Semiconductors announced their collaboration on VinFast's next-generation of automotive applications at this year's Consumer Electronics Show (CES). The collaboration supports VinFast's goal in developing smarter, cleaner and connected electric vehicles.

Under the collaboration, VinFast seeks to leverage NXP's processors, semiconductors and sensors. VinFast and NXP will engage in the early development phases of new VinFast automotive projects, leveraging NXP's rich portfolio of system solutions for innovative applications.

Additionally, NXP will share its robust partner ecosystem with VinFast, bringing its top-notch solutions to accelerate time-to market. Together the companies will establish a joint, expert collaboration dedicated to developing solutions based on NXP's renowned reference evaluation platforms and software layers with the purpose of designing and building leading-edge electric vehicles.

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